

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|-------|------------------|---------|------------------|
| L1 | 0 | "134430" | JPO | OR | ON | 2005/02/03 19:51 |
| L2 | 1 | "60134430" | JPO | OR | ON | 2005/02/03 19:52 |
| L3 | 3 | ("6411359") or ("5949502") or ("6388888").PN. | USPAT | OR | OFF | 2005/02/03 20:14 |
| L4 | 1283 | (epoxy adj resin) with (curing with heat) | USPAT | OR | ON | 2005/02/03 20:14 |
| L5 | 92 | 4 and semiconductor adj chip | USPAT | OR | ON | 2005/02/03 20:15 |
| L6 | 3 | coefficient adj curing adj shrinkage | USPAT | OR | ON | 2005/02/03 20:15 |
| L7 | 445 | (urethane with resin) and (acryl with resin) and (epoxy with resin) and (polyimide with resin) | USPAT | OR | ON | 2005/02/03 20:26 |
| L8 | 117 | 7 and (semiconductor) | USPAT | OR | ON | 2005/02/03 20:27 |
| L9 | 20 | 8 and (shrink\$3) | USPAT | OR | ON | 2005/02/03 20:40 |
| L10 | 5 | ("6528354") or ("6479318") or ("5989940") or ("6384987") or ("6468639").PN. | USPAT | OR | OFF | 2005/02/03 20:42 |
| L11 | 5 | ("6528354") or ("6479318") or ("5989940") or ("6384487") or ("6468639").PN. | USPAT | OR | OFF | 2005/02/03 20:43 |
| L12 | 2 | ("6384487") or ("6468639").PN. | USPAT | OR | OFF | 2005/02/03 20:43 |
| S1 | 1 | "6674155" | USPAT | OR | ON | 2005/02/03 19:51 |
| S2 | 1695 | 438/108.ccls. or 438/112.ccls. or 438/124.ccls. | USPAT | OR | ON | 2005/02/03 15:33 |
| S3 | 1852 | 438/125.ccls. or 438/126.ccls. or 438/127.ccls. | USPAT | OR | ON | 2005/02/03 15:12 |
| S4 | 1234 | 438/106.ccls. | USPAT | OR | ON | 2005/02/03 15:12 |
| S5 | 648 | 438/117.ccls. or 438/121.ccls. | USPAT | OR | ON | 2005/02/03 15:13 |
| S6 | 642 | S4 not (S2 or S3 or S5) | USPAT | OR | ON | 2005/02/03 15:13 |
| S7 | 4040 | S2 or S3 or S4 or S5 | USPAT | OR | ON | 2005/02/03 20:22 |
| S8 | 3515 | S7 not ("2004".ay. or "2003".ay. or "2002".ay.) | USPAT | OR | ON | 2005/02/03 15:15 |
| S9 | 351 | S8 and (polyimide with substrate) | USPAT | OR | ON | 2005/02/03 16:25 |
| S10 | 2303 | (polyimide with substrate) and ((thermal adj shrinkage) or (curing adj shrinkage) or (coefficient with (expansion or shrinkage))) | USPAT | OR | ON | 2005/02/03 16:26 |
| S11 | 1559 | S10 and (semiconductor) | USPAT | OR | ON | 2005/02/03 16:31 |
| S12 | 141 | substrate and warpage and curing and shrinkage and semiconductor | USPAT | OR | ON | 2005/02/03 16:31 |
| S13 | 83 | S12 and polyimide | USPAT | OR | ON | 2005/02/03 16:32 |
| S14 | 1 | ("6384487").PN. | USPAT | OR | OFF | 2005/02/03 16:32 |